

Features

- 0805 SMD LED
- Close responsively to the human eye spectrum
- Light to Current, analog output
- Good output linearity across wide illumination range
- Low sensitivity variation across various light sources

Applications

- Infrared application system
- Optoelectronic automatic control system
- Optoelectronic switch
- Printer
- Counters and sorters
- Encoders
- Floppy disk drive
- Video camera, tape and card readers
- Position sensors

Description

The IN-S85BTPT is a popular 0805 package with versatile design capabilities. It is a PCB type LED which can be used in various applications. Due to its clear epoxy, the device is matched to visible light and infrared radiation.

Recommended Solder Pattern

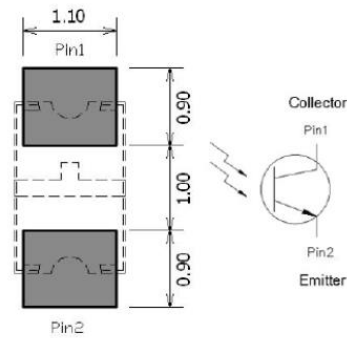
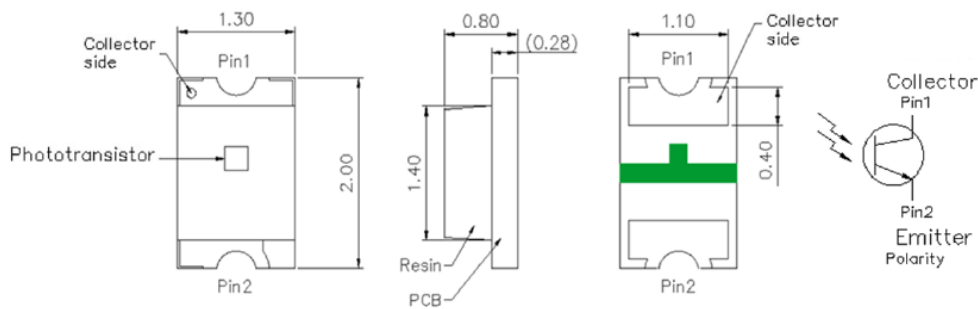


Figure 1. IN-S85BTPT Solder Pattern

Package Dimensions in mm



Notes.

1. All dimensions are in millimeters.
2. Tolerance is ± 0.10 mm unless otherwise noted

Figure 2. IN-S85BTPT Package Dimensions

Absolute Maximum Rating at 25°C

| Symbol | Parameters | Ratings | Units | Notes |
|-------------------|-------------------------------------|----------|-------|-------|
| BV _{CEO} | Collector-Emitter Breakdown Voltage | 35 | V | 1 |
| BV _{ECO} | Emitter-Collector Breakdown Voltage | 5 | V | 2 |
| I _c | Collector Current | 20 | mA | |
| T _{opr} | Operating Temperature | -40~+85 | °C | |
| T _{stg} | Storage Temperature | -40~+100 | °C | |
| T _{sol} | Soldering Temperature | 260 | °C | 3 |
| P _{to} | Total Power Dissipation | 150 | mW | |

Notes

1. Test conditions: I_c=100μA, E_e=0mW/cm².
2. Test conditions: I_E=100μA, E_e=0mW/cm².
3. Soldering time ≤ 5 seconds.

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

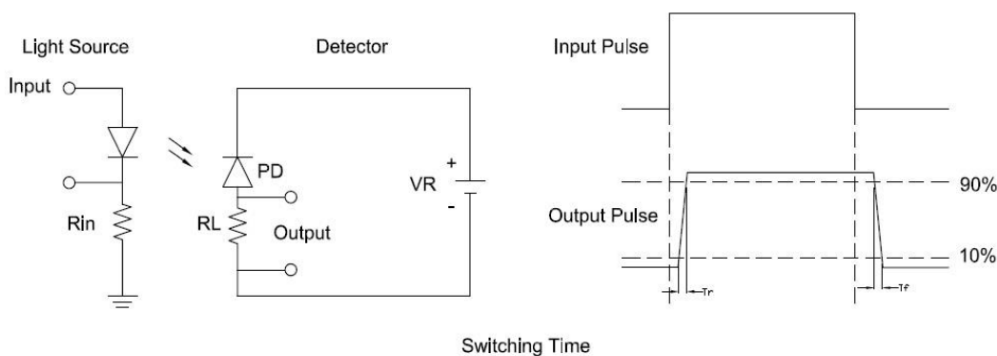
Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

Electro-Optical Characteristics

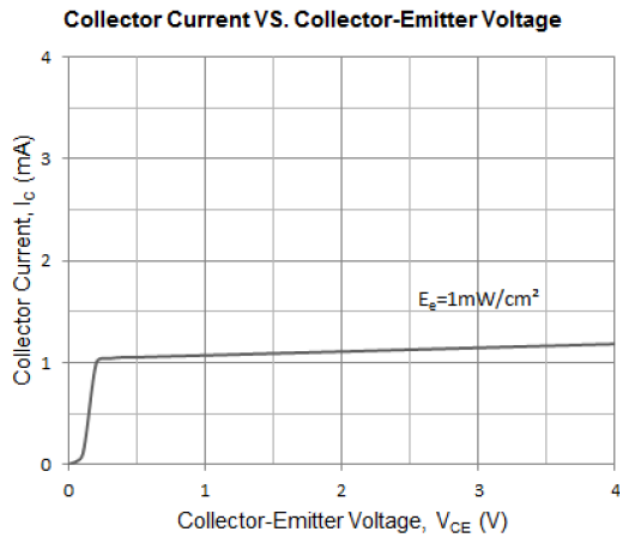
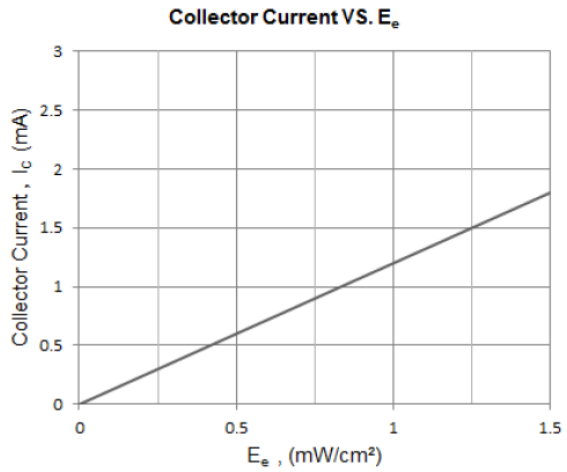
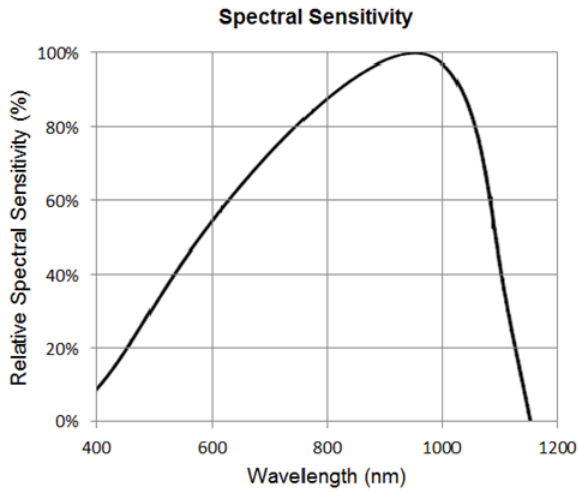
| Symbol | Parameters | Test conditions | Min | Typ | Max | Units | Notes |
|---------------|--------------------------------------|---|-----|-----|------|---------|-------|
| λ_D | Rang Of Spectral Bandwidth | --- | 400 | - | 1100 | nm | |
| λ_P | Wavelength Of Peak Sensitivity | --- | - | 940 | | nm | |
| BV_{CEO} | Collector-Emitter Breakdown Voltage | $I_C=100\mu A$ $E_e=0mW/cm^2$ | - | 35 | - | V | |
| BV_{ECO} | Emitter-Collector Breakdown Voltage | $I_E=100\mu A$ $E_e=0mW/cm^2$ | - | 5 | - | V | |
| $V_{CE(sat)}$ | Collector-Emitter Saturation Voltage | $I_C=2mA$ $E_e=1mW/cm^2$ | - | - | 0.4 | V | |
| I_{CEO} | Collector Dark Current | $V_{CE}=20V$ $E_e=0mW/cm^2$ | - | - | 100 | nA | |
| $I_{C(ON)}$ | On State Collector Current | $E_e=1mW/cm^2$ $\lambda_P=940nm,$ $V_{CE}=5V$ | 0.1 | 1.0 | 2.0 | mA | |
| t_r | Rise Time | $V_{CE}=5V,$ $I_C=1mA$ $R_L=1000\Omega$ | - | 15 | - | μS | 4 |
| t_f | Fall Time | | - | 15 | - | μS | 4 |

Notes

4. Test circuit :



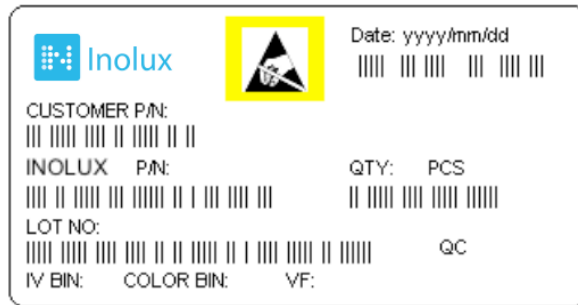
Typical Characteristic Curves



Ordering Information

| Product | Symbol | Parameters | Test conditions | Min | Typ | Max | Units | Orderable Part Number |
|------------|--------------------|----------------------------|--|-----|-----|-----|-------|-----------------------|
| IN-S85BTPT | I _{C(ON)} | On State Collector Current | E _e =1mW/cm ² λ _p =940nm, V _{CE} =5V | 0.1 | 1.0 | 2.0 | mA | IN-S85BTPT |

Label Specifications



Inolux P/N:

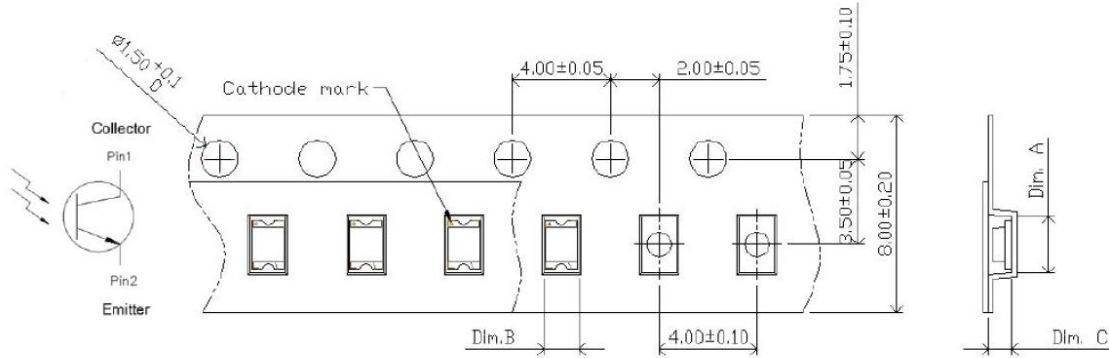
| I | N | - | S | 8 | 5 | B | T | | PT | - | - | - | - | - |
|------------|---|---|----------|-----------------|---|-----------|---------------|---------------------------------|-----------------------|----------------------|---|---|---|---|
| | | | Material | Package | | Variation | Orientation | Lens | Color | Customized Stamp-off | | | | |
| Inolux SMD | | | PCB - S | 85B= 0805 0.8mm | | | T = Top Mount | (Blank) = Clear U = Diffused | PT = Photo Transistor | | | | | |

Lot No.:

| | | | | | | | |
|------------------|--------------------------|---|---|---|-------|------|--------|
| Z | 2 | 0 | 1 | 7 | 01 | 24 | 001 |
| Internal Tracker | Year (2017, 2018,) | | | | Month | Date | Serial |

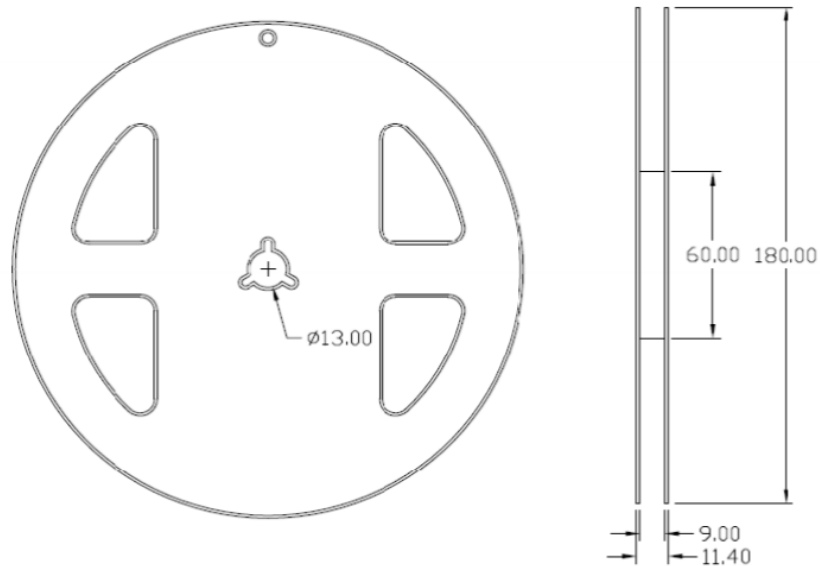
Packaging Information:

Packaging
Tape Dimension

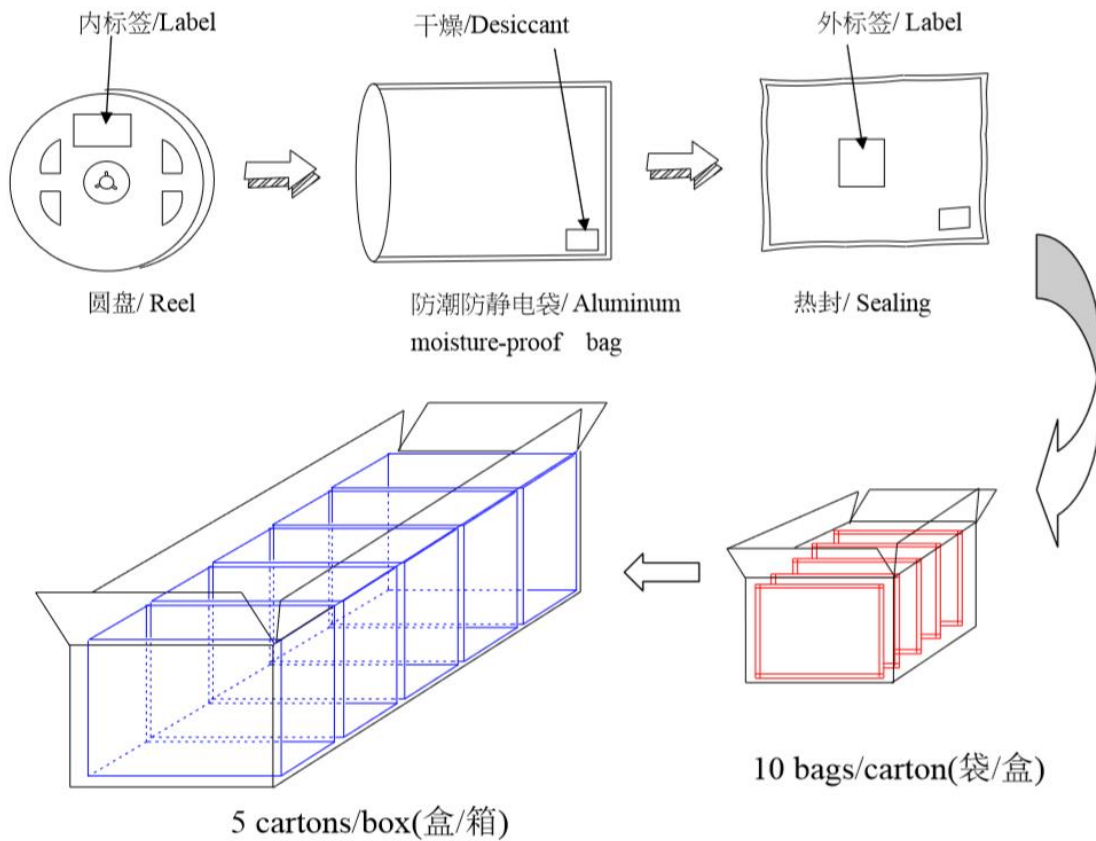


| Dim. A | Dim. B | Dim. C | Q'ty/Reel |
|-------------|-------------|-------------|-----------|
| 2.30 ± 0.05 | 1.45 ± 0.05 | 0.95 ± 0.05 | 4K |

Reel Dimension



Packing Dimension



5 boxes per carton are available depending on shipment quantity.

| | Specification | Material | Quantity |
|--------------|----------------------|-----------------------------------|------------------|
| Carrier tape | Per EIA 481-1A specs | Conductive black tape | 4000pcs per reel |
| Reel | Per EIA 481-1A specs | Conductive black | |
| Label | IN standard | Paper | |
| Packing bag | 220x240mm | Aluminum laminated bag/ no-zipper | One reel per bag |
| Carton | IN standard | Paper | Non-specified |

Others:

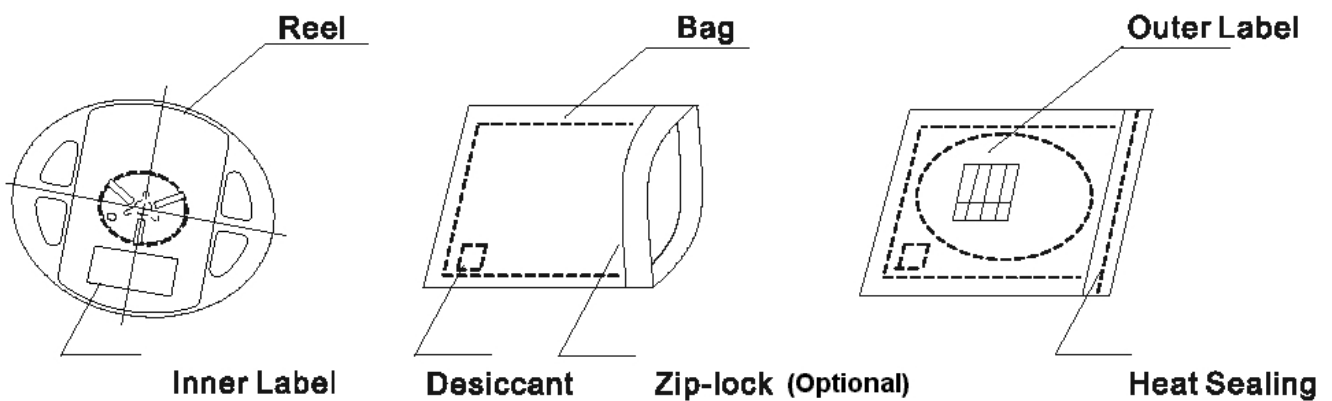
Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

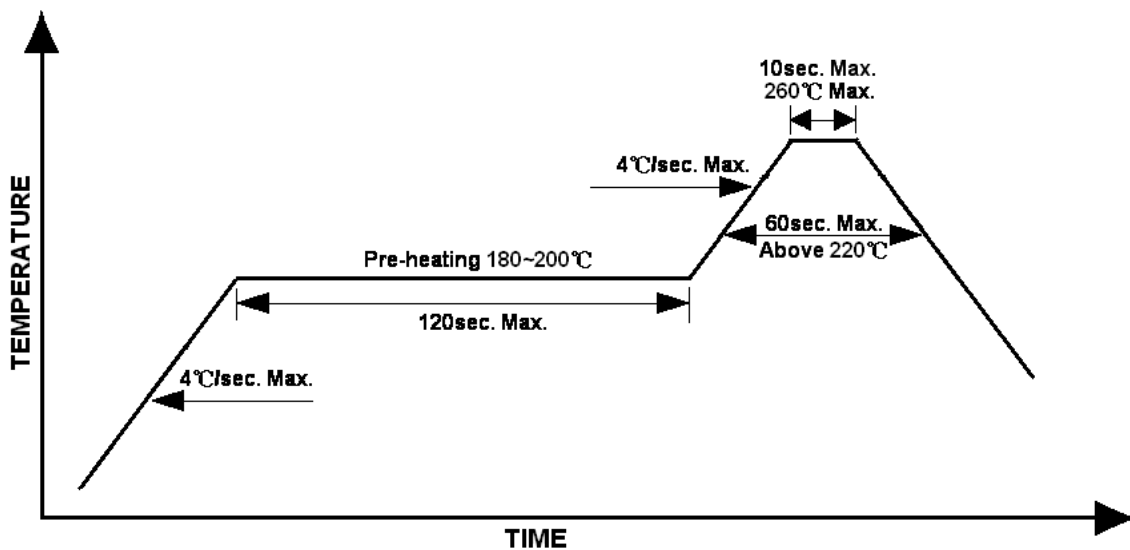
The packaging sequence is as follows:



Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Lead-free Solder Profile



Precautions

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AlInGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Reliability

| Item | Frequency/ lots/ samples/ failures | Standards Reference | Conditions |
|--------------------------------------|---|--------------------------------|--|
| Precondition | For all reliability monitoring tests according to JEDEC Level 2 | J-STD-020 | 1.) Baking at 85°C for 24hrs 2.) Moisture storage at 85°C/ 60% R.H. for 168hrs |
| Solderability | 1Q/ 1/ 22/ 0 | JESD22-B102-B And CNS-5068 | Accelerated aging 155°C/ 24hrs Tinning speed: 2.5+0.5cm/s Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s |
| Resistance to soldering heat | | CNS-5067 | Dipping soldering terminal only Soldering bath temperature A: 260+/-5°C; 10+/-1s B: 350+/-10°C; 3+/-0.5s |
| Operating life test | 1Q/ 1/ 40/ 0 | CNS-11829 | 1.) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) Tamb25°C; IF=20mA; duration 1000hrs |
| High humidity, high temperature bias | 1Q/ 1/ 45/ 0 | JESD-A101-B | Tamb: 85°C Humidity: 85% R.H., IF=5mA Duration: 1000hrs |
| High temperature bias | 1Q/ 1/ 20 | IN specs. | Tamb: 55°C IF=20mA Duration: 1000hrs |
| Pulse life test | 1Q/ 1/ 40/ 0 | | Tamb25°C, If=20mA,, Ip=100mA, Duty cycle=0.125 (tp=125 μs, T=1sec) Duration 500hrs) |
| Temperature cycle | 1Q/ 1/ 76/ 0 | JESD-A104-A IEC 68-2-14, Nb | A cycle: -40 degree C 15min; +85 degree C 15min Thermal steady within 5 min.. 300 cycles 2 chamber/ Air-to-air type |
| High humidity storage test | 1Q/ 1/ 40/ 0 | CNS-6117 | 60+3°C 90+5/-10% R.H. for 500hrs |
| High temperature storage test | 1Q/ 1/ 40/ 0 | CNS-554 | 100+10°C for 500hrs |
| Low temperature storage test | 1Q/ 1/ 40/ 0 | CNS-6118 | -40+5°C for 500hrs |